

Amendments to the Specification:

Please amend the title beginning at page 1, line 1 as follows:

--Method of Manufacturing Circuit Device Using a Communication Network--

Please replace the abstract at page 29 with the following amended abstract:

A method of manufacturing a System In Package (SIP) or Integrated System in Board (ISB) circuit device (~~SIP or ISB~~) in which a plurality of circuit elements are covered with and integrally supported by an insulating resin. A user terminal is connected with an ISB server and an ISB mounting factory through a communication network. Specifications to be satisfied by an ISB circuit device desired by a user, such as an external size and terminal information of the ISB and circuit diagram CAD data, for example, are input through the user terminal and transmitted to the ISB server. The ISB server in turn transmits information concerning the due date and cost of the ISB circuit device and also a reliability evaluation result to the user terminal. The ISB server also generates mask data for manufacturing the ISB circuit device based on the input specifications, and transmits the mask data to the ISB mounting factory. The ISB mounting factory, receiving the manufacturing data from the ISB server, manufactures the ISB circuit device and provides the ISB circuit device to the user.